ABSTRACT

A polishing method for a wafer using a polishing head having a plurality of pressure chambers formed by an elastic membrane is disclosed. The polishing method includes: forming a positive pressure in a first pressure chamber and forming a negative pressure in a second chamber to move fluid present between an upper surface of the wafer and the first pressure chamber outward; then forming a positive pressure in the second chamber and forming a negative pressure in a third pressure chamber to move the fluid present between the upper surface of the wafer and the second pressure chamber outward; then forming a positive pressure in outermost pressure chamber of the plurality of pressure chambers to move the fluid present between the upper surface of the wafer and the outermost pressure chamber outward to thereby cause the fluid to flow out from the upper surface of the wafer; and then pressing a lower surface of the wafer against a polishing surface with the elastic membrane to polish the lower surface of the wafer.

FIG. 6